

NOTES:

MATERIAL:

1. HOUSING MATERIAL: GLASS FILLED POYESTER UL94V-0.
2. CONTACT MATERIAL: PHOSPHOR BRONZE  $t=0.3\text{mm}$
3. PLATING: SELECTING GOLD PLATING  $1\mu\sim 50\mu$  OVER NICKEL IN CONTACT AREA.  $150\mu$  TIN PLATIN. OVER NICKEL IN SOLDER AREA
4. SHIELD: 0.2mm THICKNESS COPPER WITH NICKEL PLATE

ELECTRICAL

1. VOLTAGE RATING: 125V AC RMS
2. CURRENT RATING: 1.5AMP
3. CONTACT RESISTANCE: 30 MILLIOHMS MAX
4. INSULATION RESISTANCE 500 MEGOHMS MIN @500V DC
5. DIELECTRIC WITHSTANDING RESISTANCE : 1000V AC RMS 50Hz. 1MIN

MECHANICAL

1. DURRABILITY: 750 CYCLES MIN
2. PCB RETENTTON PRB-SOLDER: 1 LB MIN

REVRONMENTAL

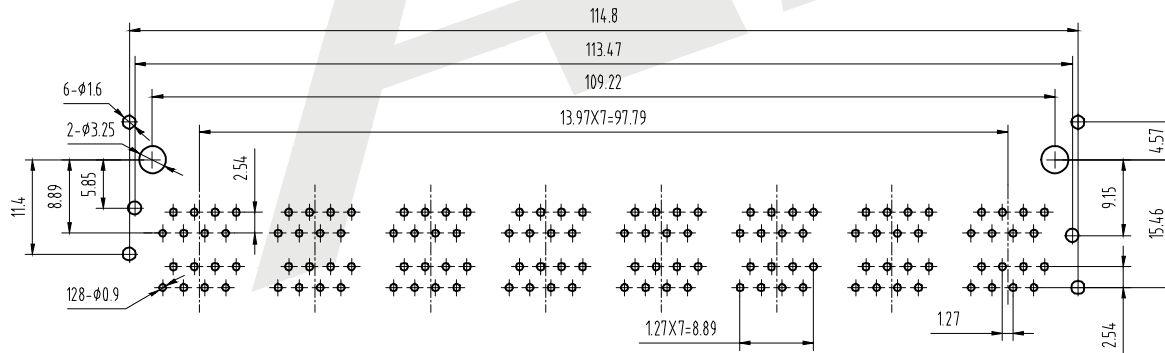
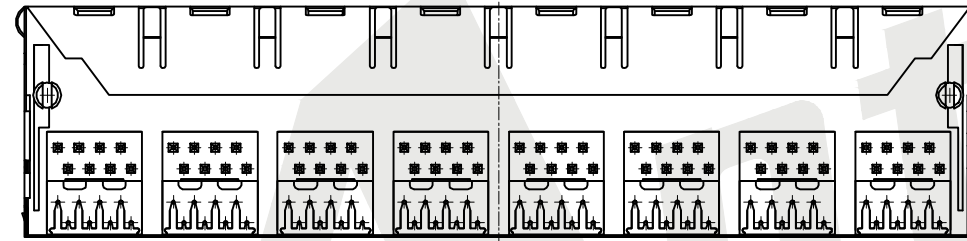
1. STORAGE:  $-40^{\circ}\text{C}$  TO  $85^{\circ}\text{C}$
2. OPERATION:  $0^{\circ}\text{C}$  TO  $70^{\circ}\text{C}$

Order code:

ATRJ5921 - 8P - 8C - X - C1 - L

①      ②      ③      ④      ⑤      ⑥

- ① SERIES NO:
- ② NUMBER OF POSITIONS (10P, 8P, 6P, 4P)
- ③ NUMBER OF CONTACTS (10C, 8C, 6C, 4C)
- ④ Contact Plating  
G0: Gold flash  
G1: 3U" Gold  
G2: 5U" Gold  
G3: 10U" Gold  
G4: 15U" Gold  
G5: 30U" Gold  
SN: Tin
- ⑤ Shield  
A: W/O Shield  
B: Half Shield  
C: Shield W/Eml  
D: Shield W/O Eml
- ⑥ Ports  
A: 1X1P    G: 2\*1P  
B: 1X2P    H: 2\*2P  
C: 1X4P    I: 2\*3P  
D: 1X5P    J: 2\*4P  
E: 1X6P    K: 2\*6P  
F: 1X8P    L: 2\*8P



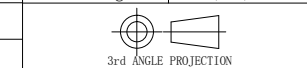
PC Board Layout  
Component Side Shown

Unless Otherwise specified tolerance  
X. ±0.35    X.XX: ±0.20  
X.X: ±0.25    X.XXX: ±0.15

**Antenk** ANTENK ELECTRONICS CO., LTD  
Http://www.antenk.com  
E-mail:sales@antenk.com

SCALE: As Shown    UNIT: mm  
DRAW Wu Feng Rong    DATE 22/03/2018  
CHECK BobYang    DATE 22/03/2018

TITLE: RJ45 Jack side entry full shielded 2X8P with EMI



DRAWING NO: ATRJ5921-8P8C-X-C1-L  
PRODUCT NO: ATRJ5921-8P8C-X-C1-L

REV	DESCRIPTION	DATE
1		
2		
3		
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